

Title (en)
IMPROVED ANNEALING METHOD FOR STABILISATION

Title (de)
VERBESSERTES ERHITZUNGSVERFAHREN ZUR STABILISATION

Title (fr)
PROCEDE PERFECTIONNE DE RECUIT DE STABILISATION

Publication
EP 1639633 A2 20060329 (FR)

Application
EP 04767314 A 20040610

Priority
• FR 2004001449 W 20040610
• FR 0306920 A 20030610

Abstract (en)
[origin: FR2856194A1] Heat treatment of a slice, made from one or several semiconductor materials mounted on a support, consists of slowly raising the temperature to a final treatment temperature. The temperature increase is effected with at least one step in order to diminish the temperature gradients on the slice and between the slice and its support, to minimize the appearance of lines in the slice. The final treatment temperature is 1100 [deg] C and the evolution of temperature may include to steps at 1050 [deg] C and 1075 [deg] C, each step having a duration of about 10 minutes.

IPC 1-7
H01L 21/762

IPC 8 full level
H01L 21/20 (2006.01); **H01L 21/324** (2006.01); **H01L 21/762** (2006.01)

CPC (source: EP US)
H01L 21/2007 (2013.01 - EP); **H01L 21/324** (2013.01 - EP US); **H01L 21/76251** (2013.01 - EP)

Citation (search report)
See references of WO 2004112124A2

Designated contracting state (EPC)
AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HU IE IT LI LU MC NL PL PT RO SE SI SK TR

DOCDB simple family (publication)
FR 2856194 A1 20041217; FR 2856194 B1 20050826; EP 1639633 A2 20060329; JP 2006527493 A 20061130; JP 4949021 B2 20120606; WO 2004112124 A2 20041223; WO 2004112124 A3 20050512

DOCDB simple family (application)
FR 0306920 A 20030610; EP 04767314 A 20040610; FR 2004001449 W 20040610; JP 2006516283 A 20040610